

# SA.31m, SA.33m, and SA.35m

Quantum<sup>™</sup> Miniature Atomic Clock (MAC)



Miniature Rubidium Atomic Clock

#### **Features**

- High precision atomic clock
- Smallest form factor (smaller than most OCXOs)
- Standard quartz oscillator pinouts
- Low power consumption
- RoHs 6/6 compliant

#### **Applications**

- Stand-alone (free-run) stable frequency source for audio equipment, LTE base stations, smart grid and enterprise network Infrastructure
- Extended holdover for CDMA and WiMAX base stations
- Stability for various other communication and transmission applications



Microsemi invented portable atomic timekeeping with QUANTUM<sup>™</sup>, the world's first family of miniature and chip scale atomic clocks.

Choose QUANTUM<sup>™</sup> class for best-inclass stability, size, weight, and power consumption.

#### Newly Enhanced Quantum<sup>™</sup> MAC SA.3X Family

The Microsemi SA.3Xm marks a major step forward in the evolution of rubidium atomic clocks. Based on a new generation of atomic clock technology, the SA.3Xm family has a unique package that enables unprecedented miniaturization in a rubidium clock. It is suitable for applications requiring compact design, low power consumption, extended aging, and precision in an economical and easily adaptable package.

#### Smallest Commercially Available Rubidium Clock

Microsemi has leveraged the significant advances in miniaturization and integration to design the world's first commercially available miniature atomic clock. The SA.3Xm has physical dimensions and packaging of a small ovenized crystal oscillator (OCXO), measuring 50.8 mm x 50.8 mm (2" × 2") and standing at a mere 18.3 mm (0.72"). The MAC is the world's first commercially available Rubidium Coherent Population Trapping atomic clock. It consumes less power and has wide-spectrum temperature operation. This makes it useful for a range of timing and synchronization applicationswireless base station, wire line network infrastructure, defense system, and test and measurement devices. The small size of the SA.3Xm enables it to be easily mounted to a PCBA.

### **SA.31m**

The SA.31m is targeted for applications that require an economical solution for frequency stability, such as audio equipment in studio applications. It can also be used as an independent frequency source for next generation base stations, smart grid infrastructure and Enterprise network infrastructure. It enables transition from costly TDM backhaul transport to economic and efficient Ethernet transport.

### SA.33m

The SA.33m has superior aging and tempco, and better stability and phase noise than the SA.31m. The SA.33m may be deployed in existing rubidium applications such as extended holdover (for CDMA / CDMA 2000 or WiMAX).

### SA.35m

The SA.35m is the premium grade of the entire SA.35m family. It has the best tempco and greatest performance amongst all the versions of the family. The SA.35m is suited for applications such as extended hold over for LTE-TDD base stations and other applications that require precision frequency and long hold-over. Economical for its performance level, the SA.35m delivers premium performance at an excellent price.

## SA.31m, SA.33m, and SA.35m

## **Specifications**

#### **Electrical Specification**

Electrical Specification				
Output Freq	uency/Waveform:	10 MHz		
		3.3 Vpp (Max = 4 Vpp)		
		ACMOS square wave (15 pF load)		
Logic Level:		VL <0.5 V, VH >2.7 V		
Logic Level:		(15 pf load)		
Rise/Fail Time:		<10 ns		
Duty Cycle:		50%+/-10%		
Phase Noise	e (SSB)			
	SA.35m/SA.33m	SA.31m		
1 Hz	<-70 dBc/Hz	<-65 dBc/Hz		
10 Hz	<-87 dBc/Hz	<-85 dBc/Hz		
100 Hz	<-114 dBc/Hz	<-112 dBc/Hz		
1 kHz	<-130 dBc/Hz	<-130 dBc/Hz		
10 kHz	<-140 dBc/Hz	<-140 dBc/Hz		
Spurious:				
Non-Harmonic:		<-85 dBc		
Temperature Coeffient [peak to peak]:				
	SA.35m	SA.33m SA.31m		
(0°C to 70°C	,	≤1E-10 ≤7E-10		
(-10°C to 75	,	≤1.5E-10 ≤1E-9		
Accuracy at shipment:		<±5E-11 (25°C)		
Retrace:		<±5E-11(on-off- on: 24 hour, 48 hour,		
		12 hour @25°C)		
Control rang	je:	,		
With analog input:		$\pm$ 1E-8, 0-5 V into 5 k $\Omega$		
With digit	al input:	±2E-8 (with resolution		
		±1E-12)		
Warm-up time:		time to <1E-9 @25°C:		
		<7.5 min (if mounted on the developer's kit		
		heat sink: ≤9 min)		
Supply voltage/current:		+5 Vdc ±0.1 Vdc,		
		Max. current <2.8 A		
Power consumption:		Warm-up: 14 W max (-10°C to +75°C);		
		(-10 C to +75 C); Operating: 8 W @ 10°C,		
		5 W @ 25°C,		
		5 W @ 75°C baseplate		
Voltage coefficient:		+5 Vdc ±0.1 Vdc:		
		Magnitude (df/f)		
Toot/otot		<2E-11 peak-to-peak		
Test/status: ACMOS:		Built-in self-test (BITE) Service/fault-unlock		
Serial Port:		Microsemi specific		
Senal Port:		serial port protocol for		
		status and control		

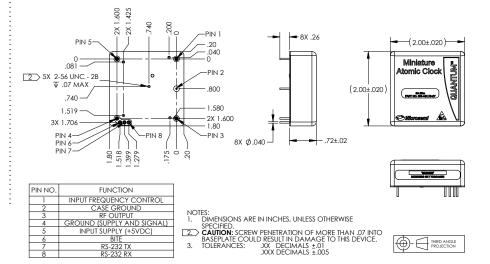
Aging:				
Туре	SA.35m/SA.33m	SA.31m		
Daily*	±2.5E-11	±4E-11		
Monthly*	±1E-10	±3E-10		
Yearly	±1E-9	±1.5E-9		
(*After 1 day and 1 month of operation respectively)				
Short Term St	ability (Allan deviation):	÷		
Туре	SA.35m / SA.33m	SA.31m		
t=1 s	≤3E-11	≤5E-11		
t=10 s	≤1.6E-11	≤2.5E-11		
t=100 s	≤8E-12	≤1E-11		
Time drift in a 24 hr period (SA.33m and SA.35m only): <7 μs over 0°C to +60°C:				
MTBF:		÷		
≥17 years @ Per Telcordia	<ul> <li>40°C (Ground, benign, 0</li> <li>40°C (Ground, fixed, GF</li> <li>SR-332, Issue 1:</li> </ul>	)		
≥20 years @ 40°C (Ground, fixed, uncontrolled)				
Connector: 5 Pins match standard OCXO configurations				
Pin 1: Input frequency control Pin 2*: Baseplate (connect to GND externally) Pin 3: Output signal Pin 4*: Ground (signal and supply) Pin 5: Input supply (+) *Pin 2 and Pin 4 are not connected together internally				
Three (3) additional pins for added functionality:				
Pin 6: BITE Pin 7: RS232 transmit (Tx) Pin 8: RS232 receive (Rx)				

#### Environmental

Operating temperature:	-10°C to +75°C base-plate
Magnetic field sensitivity:	<±7E-11/Gauss (up to ±2 Gauss)
Humidity:	GR-63-CORE, issue 4, April 2012, section 4.1.2
Vibration (operating):	7.7 grms, @ 1 hour/axis MIL-STD-810, figure 514.7E-1, category 24 (General Minimum Integrity Exposure) No loss of lock
Shock (operating):	30 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test Condition J. Frequency perturbation ≤1e-9 momentary
	momonitary
Storage and transport (non op	,
Storage and transport (non op Temperature:	,
• • • •	erating):
Temperature: Vibration (non-operating	erating): -55°C to +100°C 10.9 grms @ 1 hour/axis per MIL-STD-810, figure
Temperature: Vibration (non-operating unpackaged):	erating): -55°C to +100°C 10.9 grms @ 1 hour/axis per MIL-STD-810, figure
Temperature: Vibration (non-operating unpackaged): Shock (non-operating unpackaged):	erating): -55°C to +100°C 10.9 grms @ 1 hour/axis per MIL-STD-810, figure 514.7E-1, Cat 24 50 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test
Temperature: Vibration (non-operating unpackaged): Shock (non-operating	erating): -55°C to +100°C 10.9 grms @ 1 hour/axis per MIL-STD-810, figure 514.7E-1, Cat 24 50 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test
Temperature: Vibration (non-operating unpackaged): Shock (non-operating unpackaged): Physical	erating): -55°C to +100°C 10.9 grms @ 1 hour/axis per MIL-STD-810, figure 514.7E-1, Cat 24 50 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test Condition A

#### **RoHS** Compliance

• SA.31m, SA.33m, and SA.35m are 6/6 **RoHS** compliant



# SA.31m, SA.33m, and SA.35m

## Part Number Table

Part Number	Description
090-44310-21	SA.31m Rubidium Clock, AT Disabled
090-44310-22	SA.31m Rubidium Clock, AT Enabled
090-44330-21	SA.33m Rubidium Clock, AT Disabled
090-44330-22	SA.33m Rubidium Clock, AT Enabled
090-44330-23	SA.33m Rubidium Clock, AT Enabled ROHS 6/6 (Measured Time To Lock <7 min)
090-44330-24	SA.33m Rubidium Clock, AT Disabled ROHS 6/6 (Measured Time To Lock <7 min)
090-44350-21	SA.35m Rubidium Clock, AT Disabled
090-44350-22	SA.35m Rubidium Clock, AT Enabled
090-44300-00	SA.3Xm Developer's Kit
Note: AT= Analog Tuning	

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